

CMP WAFER CLEANING EQUIPMENT, WAFER TRANSFER ROBOT AND WAFER FLIPPING METHOD

5

Abstract

Disclosed are a CMP wafer cleaning apparatus, and a wafer transfer manipulator (6) and a wafer overturn method for same. The wafer transfer manipulator (6) includes: a transverse transfer shaft (13), with same only being located at a side of a cleaning unit; a transverse transfer carriage (14) provided on the transverse transfer shaft (13), and capable of transversely moving
10 along the transverse transfer shaft (13); a first vertical lifting shaft (15) provided on the transverse transfer carriage (14), and capable of vertically moving on the transverse transfer carriage (14); a rotary table (16) provided on the first vertical lifting shaft (15); and a first claw clamping arm (19) connected to the rotary table (16), and driven by the rotary table (16) to move
15 in a rotational manner. The CMP wafer cleaning apparatus is provided, and when the CMP wafer cleaning apparatus fails, safe storage of a polished wafer (9) can be realized. The wafer transfer manipulator (6) eliminates the possibility, in a drying process, of contamination particles on a moving component of the wafer transfer manipulator (6) being scattered onto the wafer (9).

20 FIG. 4